Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A production method of a multilayer ceramic device, comprising the steps of:

forming a green sheet by using a green sheet slurry;

forming an electrode pattern layer on said green sheet;

forming a dielectric blank pattern layer on level difference gap portion on said electrode pattern layer so as to bury the level difference on said pattern electrode layer by using an electrode level difference absorbing dielectric paste;

forming a multilayer body by stacking a plurality of stacking units, wherein the stacking unit is said green sheet formed with said dielectric blank pattern layer and said electrode pattern layer; and

firing said multilayer body;

wherein:

said green sheet slurry includes a first inorganic dielectric colorant powder and a first organic binder component;

said electrode level difference absorbing dielectric paste includes a second inorganic dielectric colorant powder and a second organic binder component; and

when a first weight ratio of the first organic binder component with respect to said first inorganic dielectric colorant powder in said green sheet slurry is (A), and a second weight ratio of the second organic binder component with respect to said second inorganic dielectric colorant powder in said electrode level difference absorbing dielectric paste is (B), said second weight ratio (B) is larger than said first weight ratio (A),

a value (B-A) obtained by subtracting the first weight ratio (A) from the second weight ratio (B) is 6.8,

said second organic binder component-includes consists of a combination of ethyl cellulose and benzylbutyl phthalate,

a weight ratio of said benzylbutyl phthalate is larger than the same of said ethyl cellulose with respect to said second inorganic dielectric colorant powder,

the weight ratio of said benzylbutyl phthalate with respect to said second inorganic dielectric colorant powder is 6.3% or more and 11.3% or less, and

a weight ratio of said first organic binder component with respect to said first inorganic dielectric colorant powder is less than 10wt% more than 3wt% and 16wt% or less.

- 2. (Original) The production method of a multilayer ceramic device as set forth in claim 1, wherein a thickness of said green sheet is made to be 3μm or thinner.
 - 3. (Canceled)
- 4. (Previously Presented) The production method of a multilayer ceramic device as set forth in claim 2, wherein said second weight ratio (B) in the electrode level difference absorbing dielectric paste is 10.8 to 15.8wt% and a weight ratio of said ethyl cellulose is 10 wt% or less with respect to said second inorganic dielectric colorant powder.
 - 5. (Canceled)
- 6. (Previously Presented) A multilayer ceramic device obtained by the production method as set forth in claim 1.
- 7. (Original) The multilayer ceramic device as set forth in claim 6, wherein an interlayer thickness is 2.5μm or thinner.
 - 8-11. (Canceled)
- 12. (Previously Presented) A multilayer ceramic device obtained by the production method as set forth in claim 2.

- 13. (Currently Amended) A multilayer ceramic device obtained by the production method as set forth in claim 3 claim 16.
- 14. (Previously Presented) A multilayer ceramic device obtained by the production method as set forth in claim 4.
 - 15. (Canceled)
- 16. (Previously Presented) The production method of a multilayer ceramic device as set forth in claim 1, wherein said first organic binder component includes a polyvinyl butyral resin (PVB) and dioctyl phthalate (DOP).
- 17. (Previously Presented) The production method of a multilayer ceramic device as set forth in claim 16, wherein a thickness of said green sheet is made to be 3µm or thinner.
- 18. (Currently Amended) A production method of a multilayer ceramic device, comprising:

forming a green sheet by using a green sheet slurry;

forming an electrode pattern layer on said green sheet;

forming a dielectric blank pattern layer on level difference gap portion on said electrode pattern layer so as to bury the level difference on said pattern electrode layer by using an electrode level difference absorbing dielectric paste;

forming a multilayer body by stacking a plurality of stacking units, wherein the stacking unit is said green sheet formed with said dielectric blank pattern layer and said electrode pattern layer; and

firing said multilayer body;

wherein:

said green sheet slurry includes a first inorganic dielectric colorant powder and a first organic binder component;

said electrode level difference absorbing dielectric paste includes a second inorganic dielectric colorant powder and a second organic binder component; and

when a first weight ratio of the first organic binder component with respect to said first inorganic dielectric colorant powder in said green sheet slurry is (A), and a second weight ratio of the second organic binder component with respect to said second inorganic dielectric colorant powder in said electrode level difference absorbing dielectric paste is (b),

said second weight ratio (B) is larger than said first weight ratio (A),

a value (B-A) obtained by subtracting the first weight ratio (A) from the second weight ratio (B) is 6.8,

said second organic binder component-includes consists of a combination of ethyl cellulose and benzylbutyl phthalate,

a weight ratio of said benzylbutyl phthalate is larger than the same of said ethyl cellulose with respect to said second inorganic dielectric colorant powder,

the weight ratio of said benzylbutyl phthalate with respect to said ethyl cellulose in said second organic binder component is 140wt% to 250wt%, and

a weight ratio of said first organic binder component with respect to said first inorganic dielectric colorant powder is less than 10wt% more than 3wt% and 16wt% or less.

- 19. (Previously Presented) A multilayer ceramic device obtained by the production method as set forth in claim 18.
- 20. (Previously Presented) The multilayer ceramic device as set forth in claim 18, wherein an interlayer thickness is 2.5μm or thinner.